





### **Applications**

- · Point to Point Radio / VSAT
- Millimeter-wave Communications
- Test Equipment



32-pin 5x5mm package

#### **Product Features**

• Frequency range: 13.4 – 14.4 GHz

Tune Voltage: 2 – 13 V

• Output power: 9 dBm Typical

Phase Noise: -110 dBc/Hz@100 KHz Typical

-134 dBc/Hz@1 MHz Typical

• RFout/2 Frequency Range: 6.7 - 7.2 GHz

• RFout/2 Output Power: 6 dBm Typical

• Bias: Vcc = 5V, Icc = 175 mA Typical

Technology: TriQuint HBT

Dimension: 5 x 5 x 0.85 mm

## **General Description**

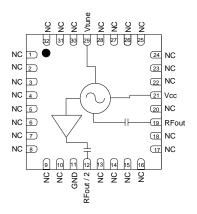
The TriQuint TGV2566-SM is a monolithic voltage controlled oscillator (VCO) designed to operate at frequencies that target the Point to Point, VSAT, and millimeter-wave communication markets.

The TGV2566-SM is manufactured on TriQuint's GaAs InGaP production process and typically provides 9 dBm output power at 14 GHz with a -110dBc/Hz phase noise at 100 KHz offset. A divide-by-2 output is provided for the PLL function.

Lead-free and RoHS compliant.

Evaluation Boards are available upon request.

## **Functional Block Diagram**



## **Pin Configuration**

Pin #	Function Label
1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 13, 14, 15, 16, 17, 18, 20, 22, 23, 24, 25, 26, 27, 28, 30, 31, 32	NC
11	GND
12	RFout/2
19	RFout
21	Vcc
29	Vtune

## **Ordering Information**

Part No.	ECCN	Description
TGV2566-SM	EAR99	13.4 – 14.4 GHz VCO with Divide by 2

Standard T/R size = 500 pieces on a 7.0" reel.

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### **Specifications**

## **Absolute Maximum Ratings**

Parameter	Rating
Supply Voltage, Vcc	+5.5V
Tuning Voltage, Vtune	+14V
Power Dissipation, Pdiss	1.2W
Junction Temperature	200°C
Storage Temperature	-65 to 125°C

Operation of this device outside the parameter ranges given above may cause permanent damage.

## **Recommended Operating Conditions**

Parameter	Min	Тур	Max	Units
Operating Temp. Range	-40	+25	+85	°C
Supply Voltage, Vcc	4.8	5.0	5.2	V
Supply Current, Icc		175		mA
Tuning Voltage, Vtune	1.5		13	V

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

## Electrical Specifications

Test conditions unless otherwise noted: Temp = +25 °C, Vcc = 5 V, Icc = 175mA

Parameter	Conditions	Min	Тур	Max	Units
Operational Frequency		13.4		14.4	GHz
RFout/2 Output Frequency		6.7		7.2	GHz
Supply Voltage, Vcc			5		V
Supply Current, Icc			175		mA
Output Power			9		dBm
RFout/2 Output Power			6		dBm
Tuning Sensitivity	Vtune = 5V		190		MHz/V
Output Return Loss			8		dB
RFout/2 Output Return Loss			5		dB
Tuning Voltage		1.5		13	V
Pushing	Vtune = 5V		8		MHz/V
Pulling	VSWR 2:1		5		MHz (p-p)
Harmonics Freq/2 3*Freq/2 2*Freq			24 32 20		dBc
Phase Noise @ 10KHz Offset	Vtune = 5V		-80		dBc/Hz
Phase Noise @ 100KHz Offset	Vtune = 5V		-110		dBc/Hz
Phase Noise @ 1MHz Offset	Vtune = 5V		-134		dBc/Hz
Frequency Drift Rate			-1.2		MHz/°C
Vtune Leakage	Vtune = 13V			7	μA

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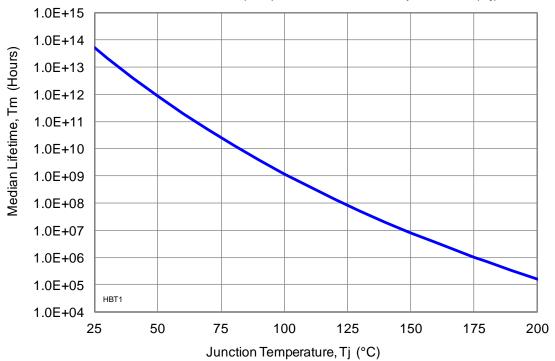


# **Specifications**

# Thermal and Reliability Information

Parameter	Condition	Rating
Thermal Resistance, $\theta_{\text{JC}}$ , measured to back of package	Tbase = 85 °C	$\theta_{JC} = 48  ^{\circ}\text{C/W}$
Junction Temperature (Tj), and Median Lifetime (Tm)	Tbase = 85 °C Vcc = 5V Icc = 175mA	Tch = 127 °C Tm = 6.9 E+7 Hours





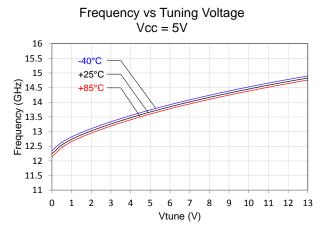
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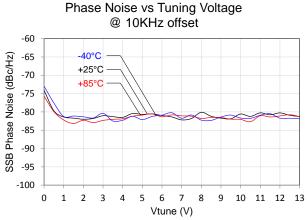
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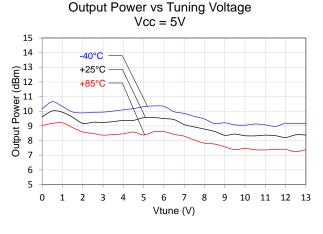
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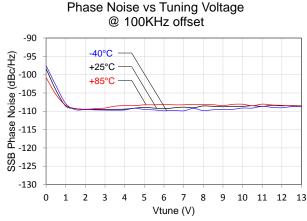


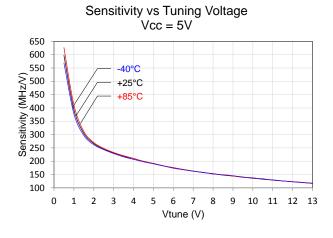
## **Typical Performance**

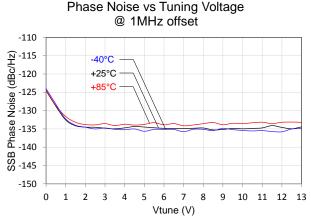






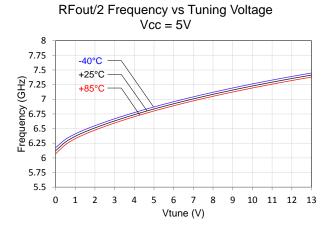


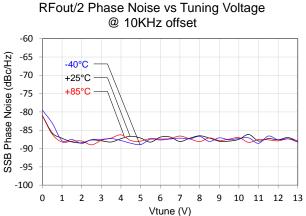


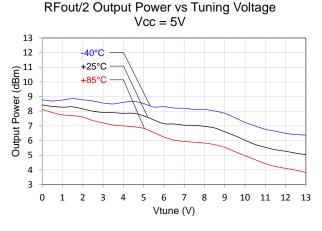


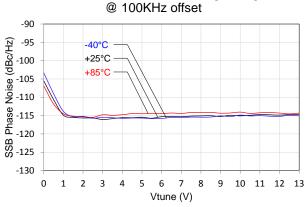


# Typical Performance

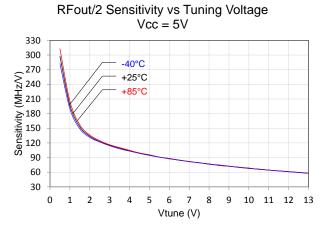


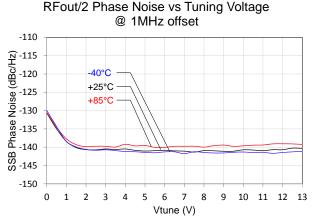






RFout/2 Phase Noise vs Tuning Voltage

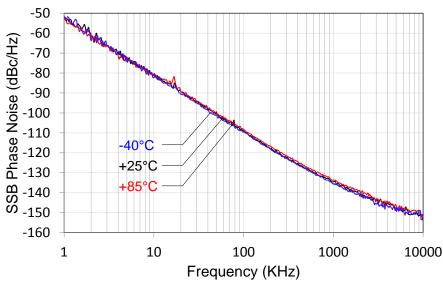






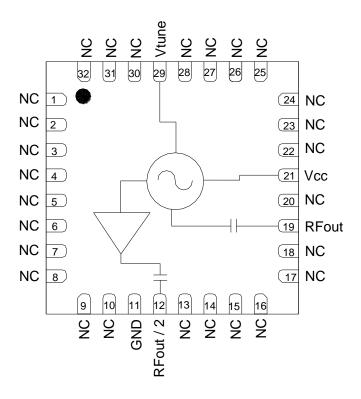
## **Typical Performance**

Phase Noise vs Offset Frequency Vcc = 5V





## **Pin Configuration and Description**

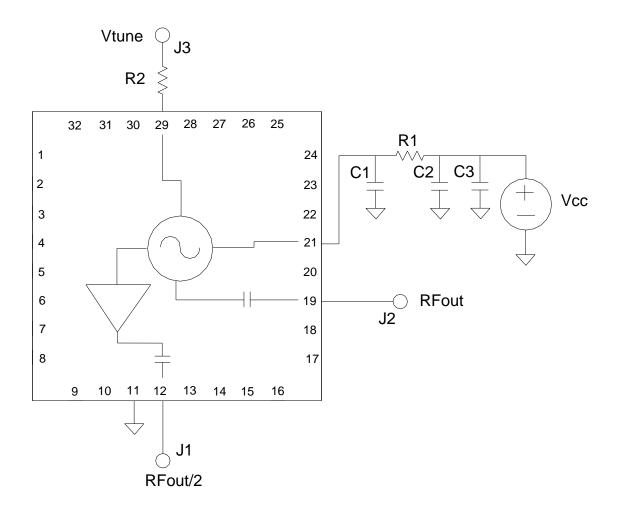


Pin	Symbol	Description
1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 13, 14, 15, 16, 17, 18, 20, 22, 23, 24, 25, 26, 27, 28, 30, 31, 32	NC	No internal connection.
11	GND	Backside Paddle. Multiple vias should be employed to minimize inductance and thermal resistance.
12	RFout/2	Frequency/2 Output match to 50 ohms, AC coupled.
19	RFout	Output, matched to 50 ohms, AC coupled.
21	Vcc	Supply voltage. Bias network is required; see Application Circuit on page 8 as an example.
29	Vtune	VCO tuning voltage.

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# **Application Circuit**



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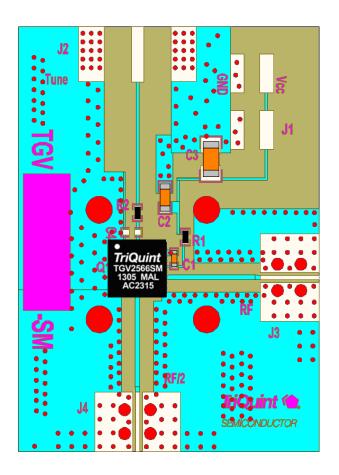


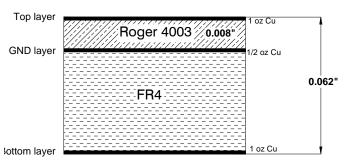
# **Application Circuit**

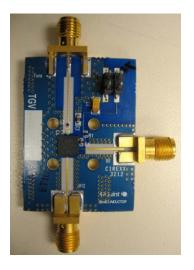
## **PC Board Layout**

Top RF layer is 0.008" thick Roger RO4003,  $\varepsilon_r = 3.38$ . Microstrip 50Ω line detail: width =0.0175". For further technical information, refer to the TGV2566-SM Product Information page.

The pad pattern shown has been developed and tested for optimized assembly at Triquint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerance. Since surface mount processes vary from company to company, careful process development is recommended.







#### **Bill of Material**

Ref Des	Value	Description	Manufacturer	Part Number
C1	100 pF	Ceramic Cap, 0402	various	
C2	1 µF	Ceramic Cap, 0603	various	
C3	10 μF	Tantalum Cap, 0805/1206	various	
R1, R2	0 ohm	Chip Res, 0402	various	

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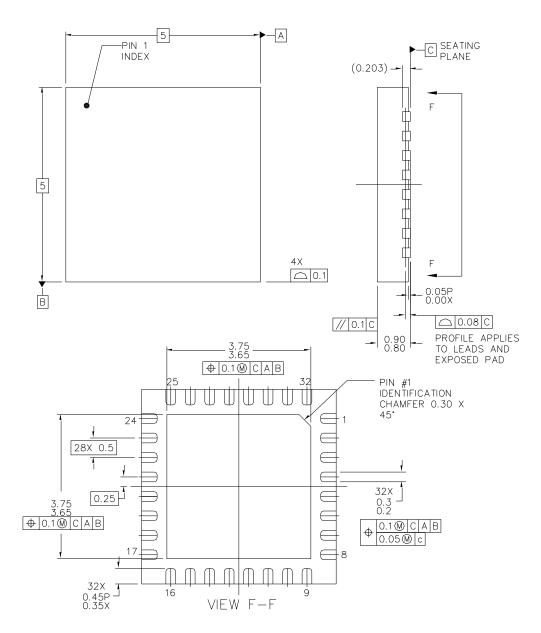
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### **Mechanical Information**

### **Package Marking and Dimensions**

All dimensions are in millimeters.



This package is lead-free/RoHS-compliant. The package base is copper alloy and the plating material on the leads is 100% matte Sn. It is compatible with both lead-free (maximum 260 °C reflow temperature) and tin-lead (maximum 245 °C reflow temperature) soldering processes.

The TGV2566-SM will be marked with the "TGV2566SM" designator and date code is marked below the part designator. The first two digits represent the last two digits of the year the part was manufactured, and the next two digits represent the work week.

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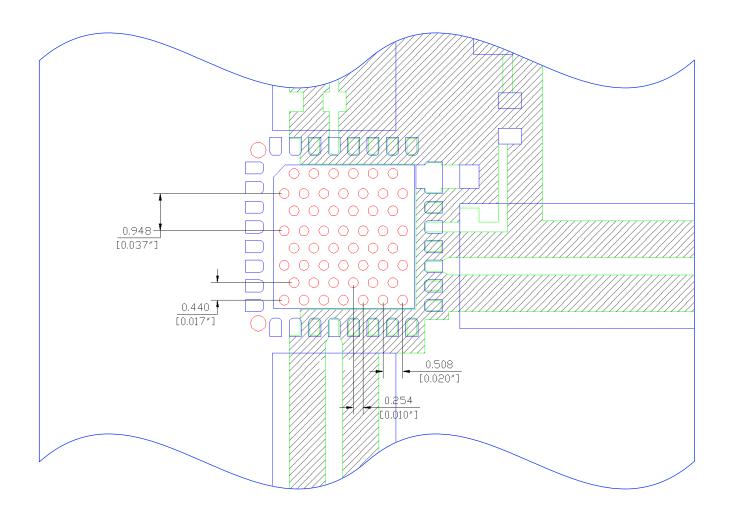
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### **Mechanical Information**

## **PCB Mounting Pattern**

All dimensions are in millimeters [inches].



#### Notes:

- 1. The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.
- 2. Ground / thermal vias are critical for the proper performance of this device. Vias have a final plated thru diameter of .25 mm (.010").

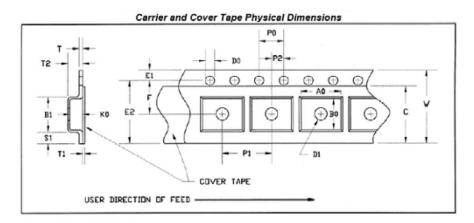
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## Tape and Reel Information

Tape and reel specifications for this part are also available on the TriQuint website in the "Application Notes" section.

Standard T/R size = 500 pieces on a 7.0" reel.



#### CARRIER AND COVER TAPE DIMENSIONS

Part	Feature	Symbol	Size (in)	Size (mm)
Cavity	Length	A0	0.207	5.25
	Width	B0	0.207	5.25
	Depth	K0	0.043	1.1
	Pitch	P1	0.315	8.00
Distance Between Centerline	Cavity to Perforation Length Direction	P2	0.079	2.00
	Cavity to Perforation Width Direction	F	0.217	5.50
Cover Tape	Width	С	0.374	9.50
Carrier Tape	Width	W	0.472	12.00

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### **Product Compliance Information**

#### **ESD Information**



Caution! ESD-Sensitive Device

**ESD** Rating: Class 1A

Value: Passes > 250V min Test: Human Body Model (HBM) JEDEC Standard JESD22-A114 Standard:

### **MSL Rating**

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Moisture Sensitivity Level (MSL) 3 at 260°C convection reflow per JEDEC standard IPC/JEDEC J-STD-020.

## **Solderability**

Compatible with both lead-free (260 °C max. reflow temp.) and tin/lead (245 °C max. reflow temp.) soldering processes.

Package lead plating: matte Sn

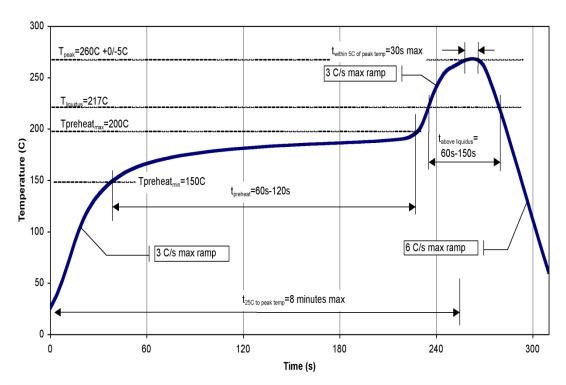
## **RoHS Compliance**

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances Electrical in Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C<sub>15</sub>H<sub>12</sub>Br<sub>4</sub>O<sub>2</sub>) Free
- **PFOS Free**
- **SVHC Free**

# **Recommended Soldering Temperature Profile**



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## **TGV2566-SM**

## 13.4 - 14.4 GHz VCO with Divide by 2

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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